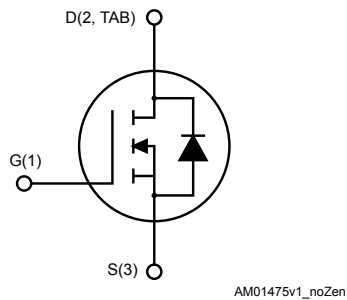
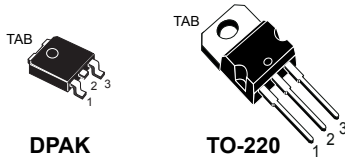


N-channel 550 V, 0.150 Ω typ., 16 A MDmesh™ M5 Power MOSFETs in a DPAK and TO-220 packages



Features

Order code	V_{DS} @ $T_{jmax.}$	$R_{DS(on)max.}$	Package
STD18N55M5	600 V	0.192 Ω	DPAK
STP18N55M5			TO-220

- Extremely low $R_{DS(on)}$
- Low gate charge and input capacitance
- Excellent switching performance
- 100% avalanche tested

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs based on the MDmesh™ M5 innovative vertical process technology combined with the well-known PowerMESH™ horizontal layout. The resulting products offer extremely low on-resistance, making them particularly suitable for applications requiring high power and superior efficiency.

Product status link

[STD18N55M5](#)
[STP18N55M5](#)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	16	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	10	A
$I_{DM}^{(1)}$	Drain current (pulsed)	64	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^{\circ}\text{C}$	110	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
T_J	Operating junction temperature range	-55 to 150	$^{\circ}\text{C}$
T_{stg}	Storage temperature range		

1. Pulse width limited by safe operating area.

2. $I_{SD} \leq 16\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$; $V_{DS\ peak} < V_{(BR)DSS}$; $V_{DD} = 340\text{ V}$.

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		DPAK	TO-220	
$R_{thj-case}$	Thermal resistance junction-case	1.14		$^{\circ}\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient		62.5	$^{\circ}\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50		$^{\circ}\text{C}/\text{W}$

1. When mounted on an 1-inch² FR-4, 2oz Cu board.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_J\text{ Max}$)	4	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25\text{ }^{\circ}\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	210	mJ

2 Electrical characteristics

($T_{CASE} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	550			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 550\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 550\text{ V}$, $T_C = 125\text{ }^{\circ}\text{C}^{(1)}$			100	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$, $I_D = 8\text{ A}$		0.150	0.192	Ω

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	1260	-	pF
C_{oss}	Output capacitance			42		
C_{rss}	Reverse transfer capacitance			3.6		
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }440\text{ V}$, $V_{GS} = 0\text{ V}$	-	103	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	35	-	pF
R_g	Gate input resistance	$f = 1\text{ MHz}$ open drain	-	2.8	-	Ω
Q_g	Total gate charge	$V_{DD} = 440\text{ V}$, $I_D = 8\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 18. Test circuit for gate charge behavior)	-	31	-	nC
Q_{gs}	Gate-source charge			8.3		
Q_{gd}	Gate-drain charge			14.2		

1. Time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

2. Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$t_{d(v)}$	Voltage delay time	$V_{DD} = 400\text{ V}$, $I_D = 10.5\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ (see Figure 19. Test circuit for inductive load switching and diode recovery times and Figure 22. Switching time waveform)	-	37	-	ns
$t_{r(v)}$	Voltage rise time			7		
$t_{c(off)}$	Crossing time			10.3		
$t_{f(i)}$	Current fall time			8.3		

Table 7. Source drain diode

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		16	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				64	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 16\text{ A}$, $V_{GS} = 0\text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 16\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ (see Figure 19. Test circuit for inductive load switching and diode recovery times)	-	244		ns
Q_{rr}	Reverse recovery charge			2.8		μC
I_{RRM}	Reverse recovery current			23		A
t_{rr}	Reverse recovery time	$I_{SD} = 16\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 19. Test circuit for inductive load switching and diode recovery times)	-	295		ns
Q_{rr}	Reverse recovery charge			3.7		μC
I_{RRM}	Reverse recovery current			25		A

1. Pulse width limited by safe operating area.

2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics curves

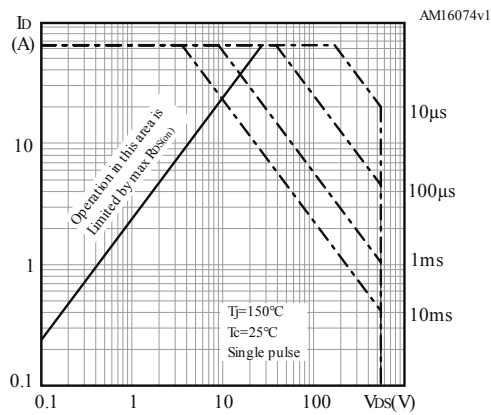
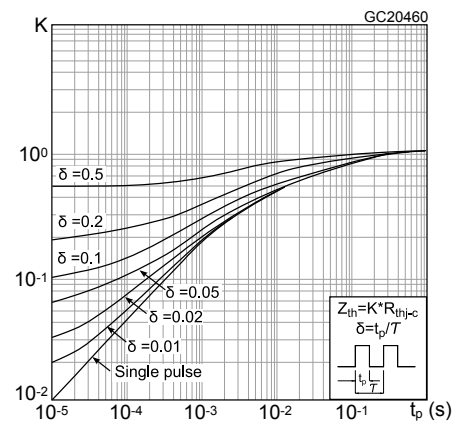
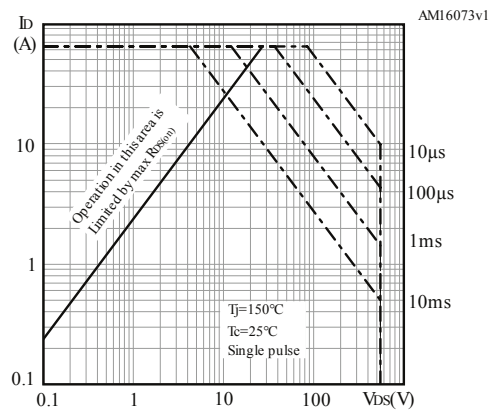
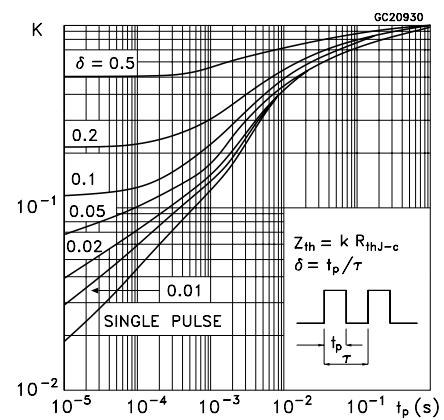
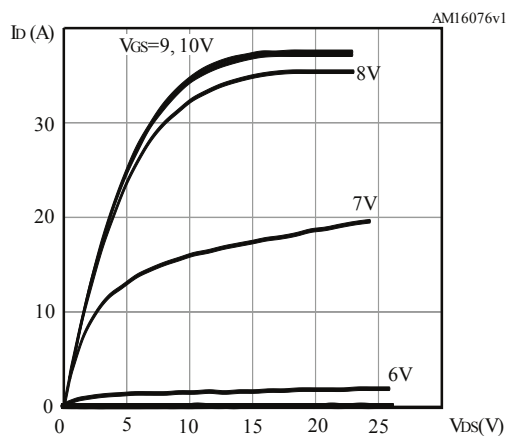
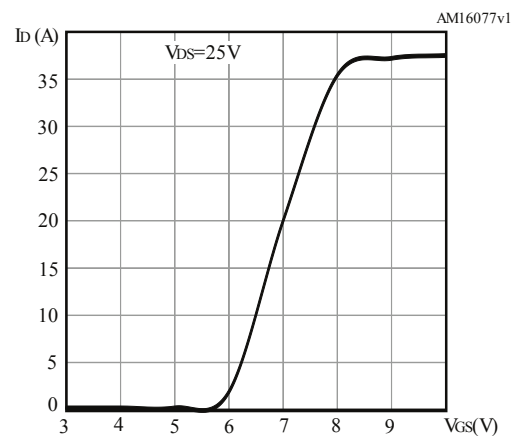
Figure 1. Safe operating area for DPAK

Figure 2. Thermal impedance DPAK

Figure 3. Safe operating area for TO-220

Figure 4. Thermal impedance for TO-220

Figure 6. Output characteristics

Figure 7. Transfer characteristics


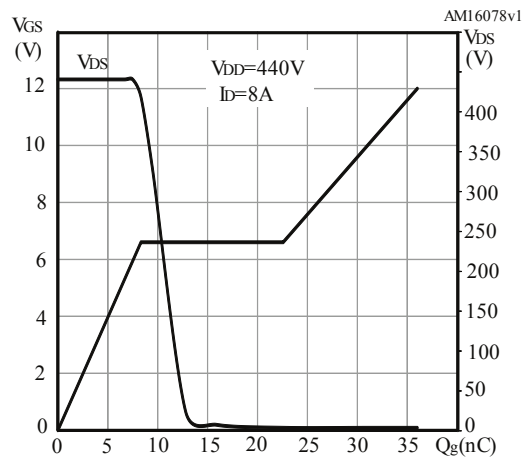
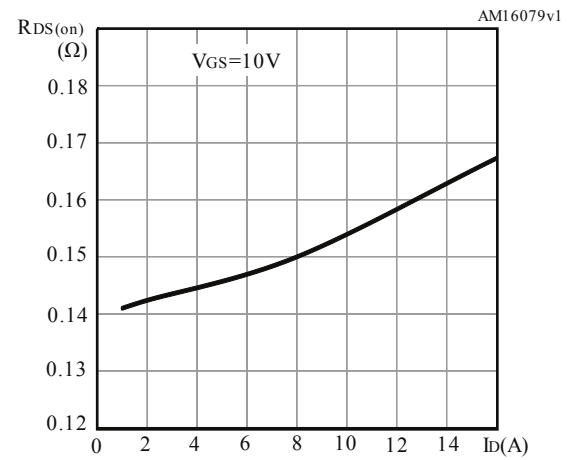
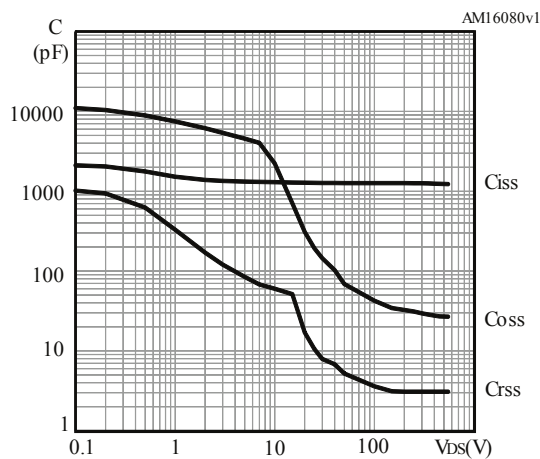
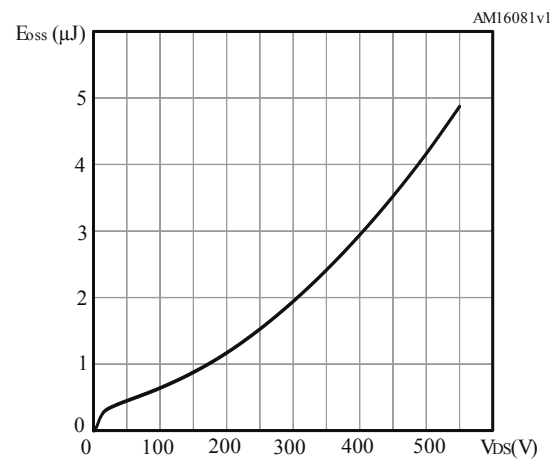
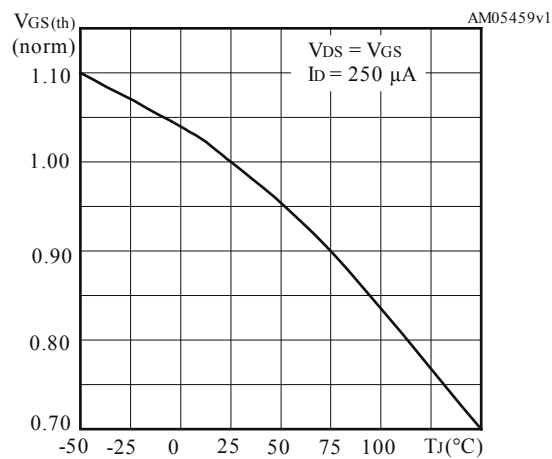
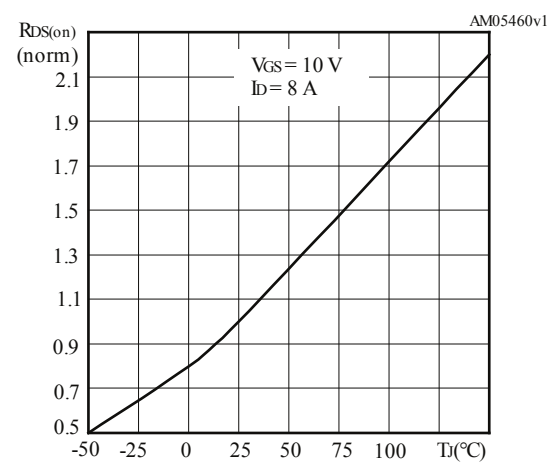
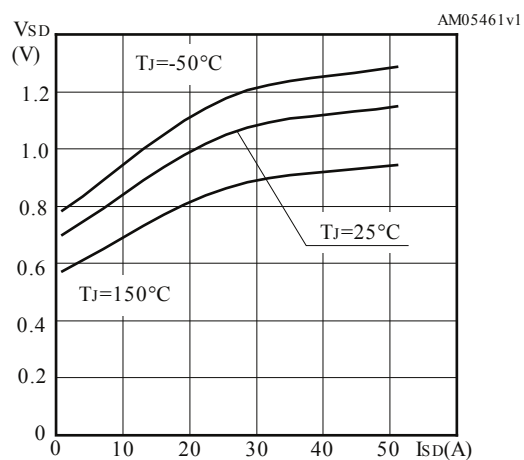
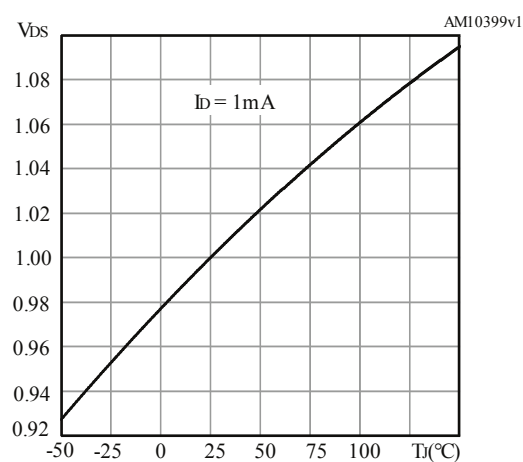
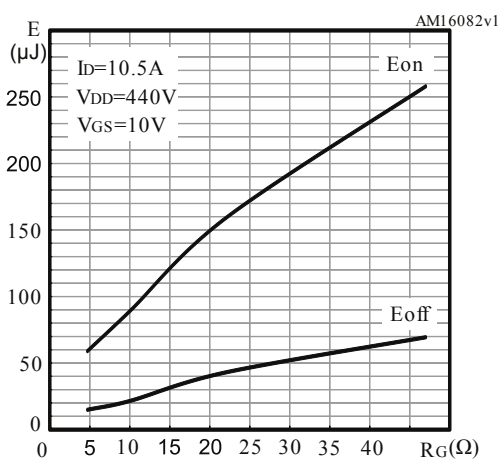
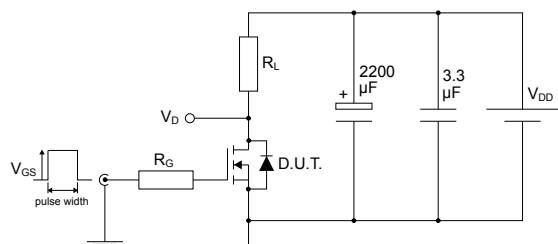
Figure 8. Gate charge vs gate-source voltage

Figure 9. Static drain-source on resistance

Figure 10. Capacitance variations

Figure 11. Output capacitance stored energy

Figure 12. Normalized on-resistance vs temperature

Figure 13. Normalized gate threshold voltage vs temperature


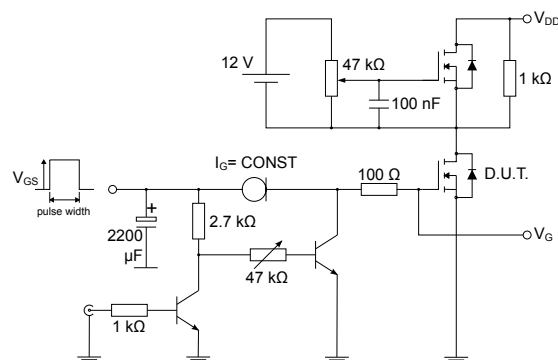
Figure 14. Drain-source diode forward characteristics

Figure 15. Normalized $V_{(BR)DSS}$ vs temperature

Figure 16. Switching energy vs gate resistance


* Eon including reverse recovery of a SiC diode

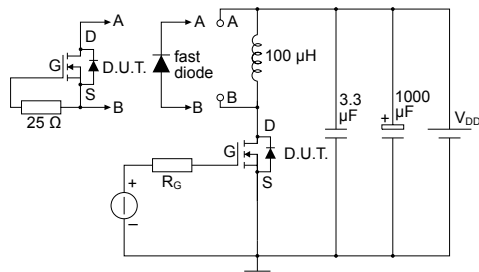
3 Test circuits

Figure 17. Test circuit for resistive load switching times


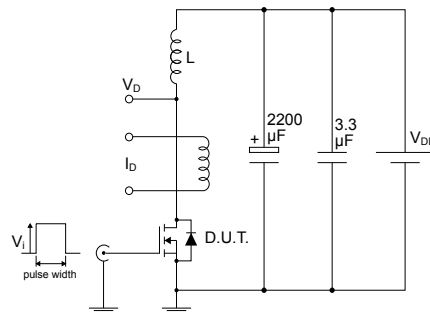
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Figure 18. Test circuit for gate charge behavior


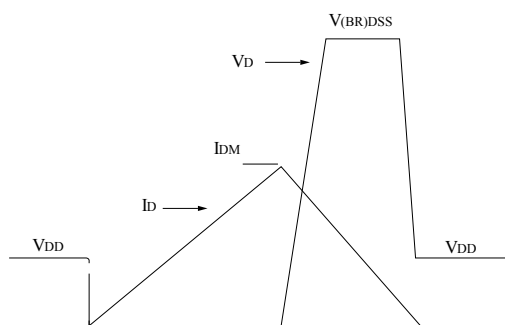
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Figure 19. Test circuit for inductive load switching and diode recovery times


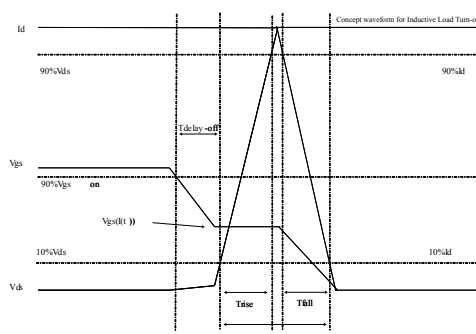
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Figure 20. Unclamped inductive load test circuit


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Figure 21. Unclamped inductive waveform


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Figure 22. Switching time waveform


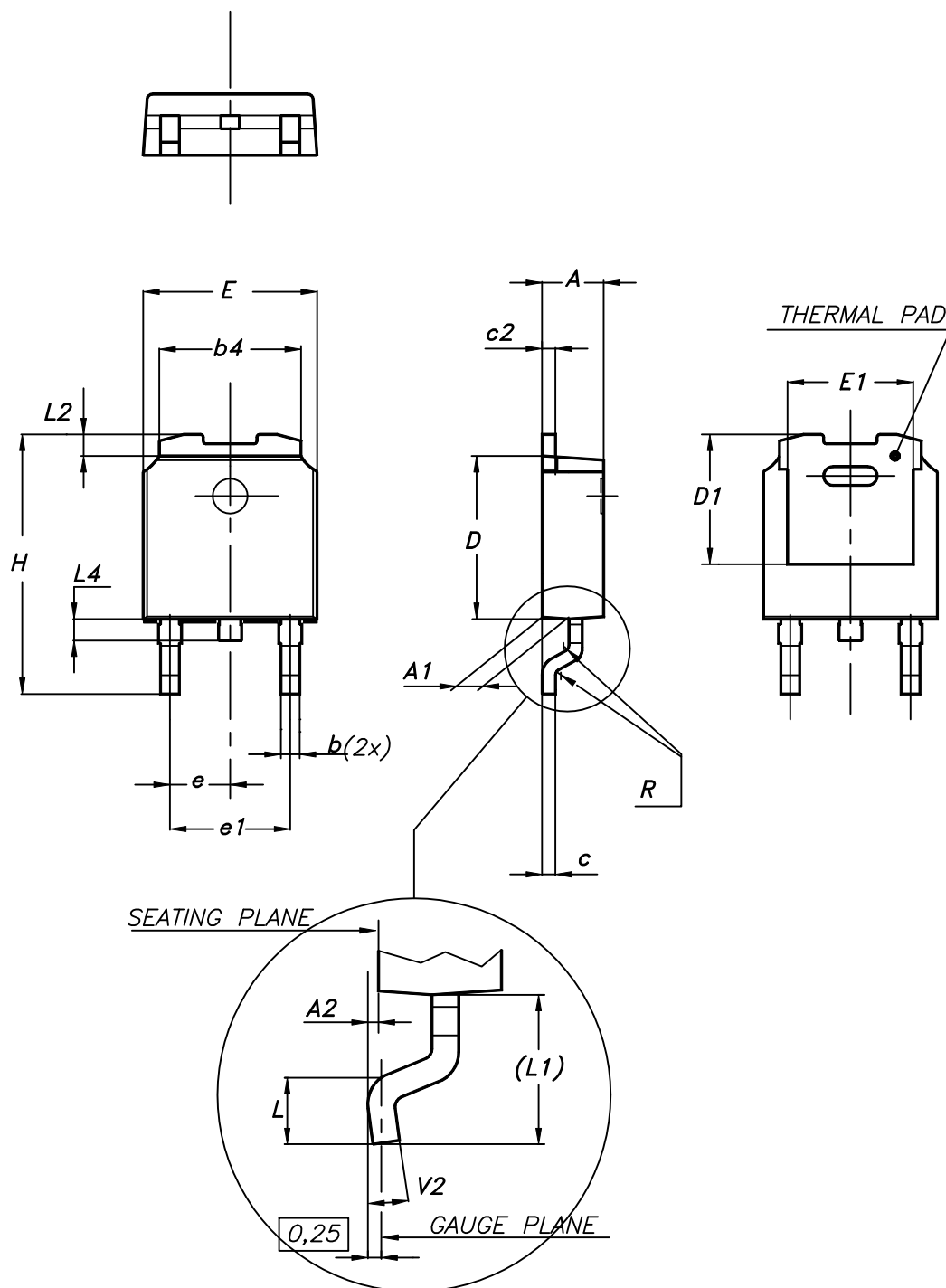
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A2 package information

Figure 23. DPAK (TO-252) type A2 package outline



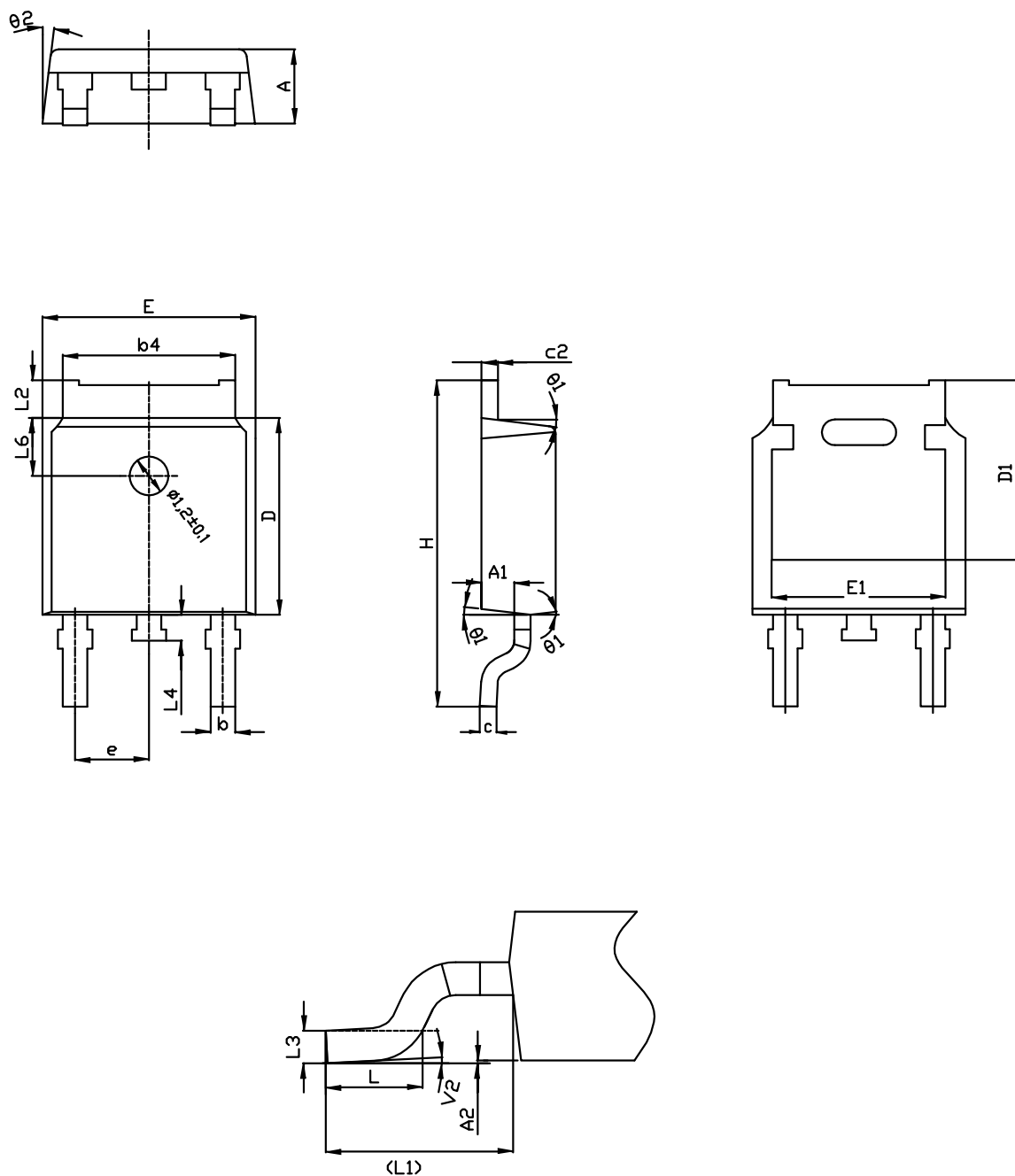
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Table 8. PAK (TO-252) type A2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

4.2 DPAK (TO-252) type C2 package information

Figure 24. DPAK (TO-252) type C2 package outline



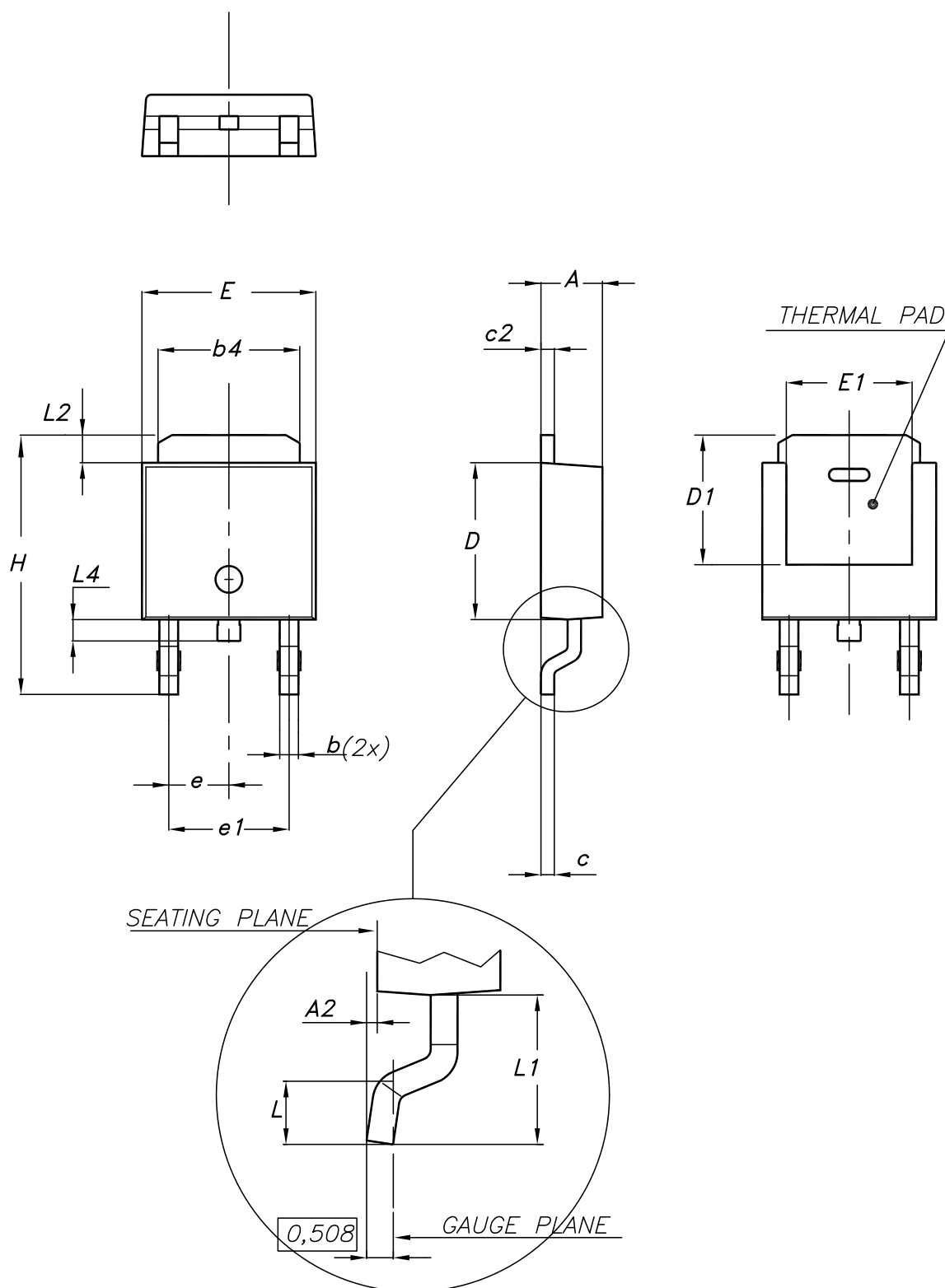
0068772_C2_25

Table 9. DPAK (TO-252) type C2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20		5.50
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

4.3 DPAK (TO-252) type E package information

Figure 25. DPAK (TO-252) type E package outline

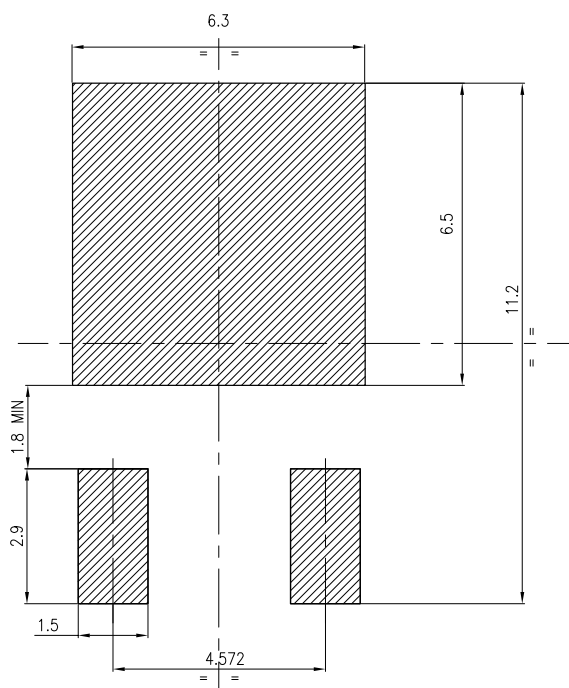


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Table 10. DPAK (TO-252) type E mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.18		2.39
A2			0.13
b	0.65		0.884
b4	4.95		5.46
c	0.46		0.61
c2	0.46		0.60
D	5.97		6.22
D1	5.21		
E	6.35		6.73
E1	4.32		
e		2.286	
e1		4.572	
H	9.94		10.34
L	1.50		1.78
L1		2.74	
L2	0.89		1.27
L4			1.02

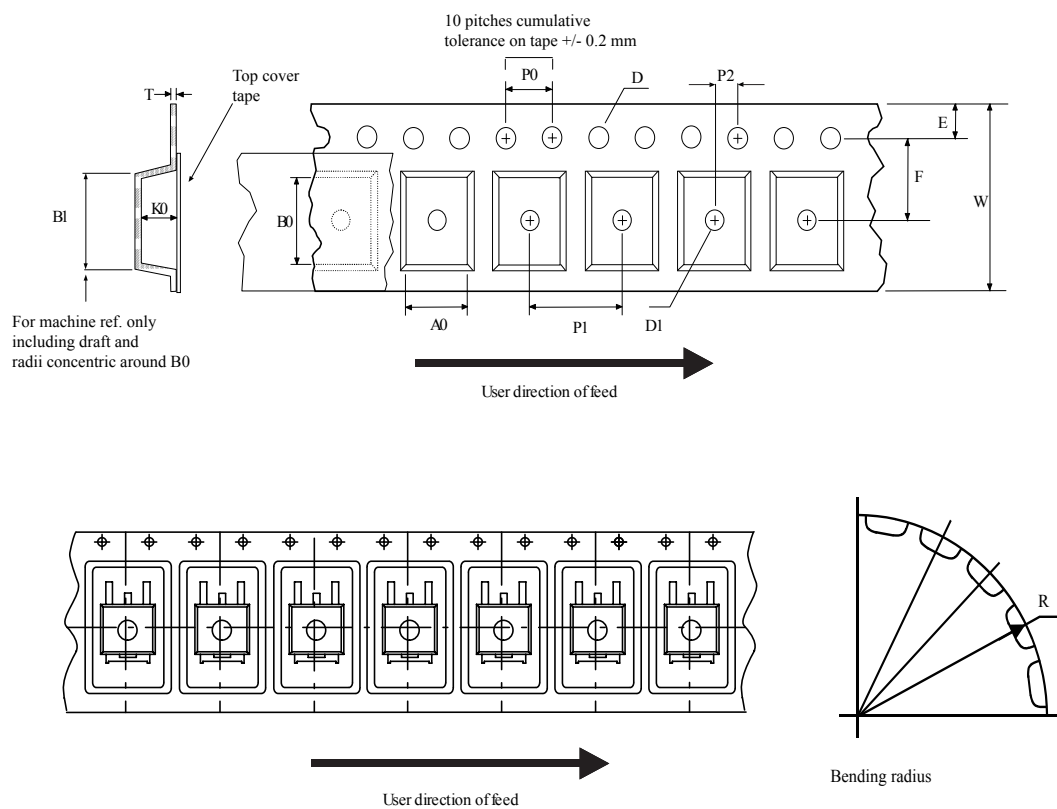
Figure 26. DPAK (TO-252) recommended footprint (dimensions are in mm)



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4.4 DPAK (TO-252) packing information

Figure 27. DPAK (TO-252) tape outline



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Figure 28. DPAK (TO-252) reel outline

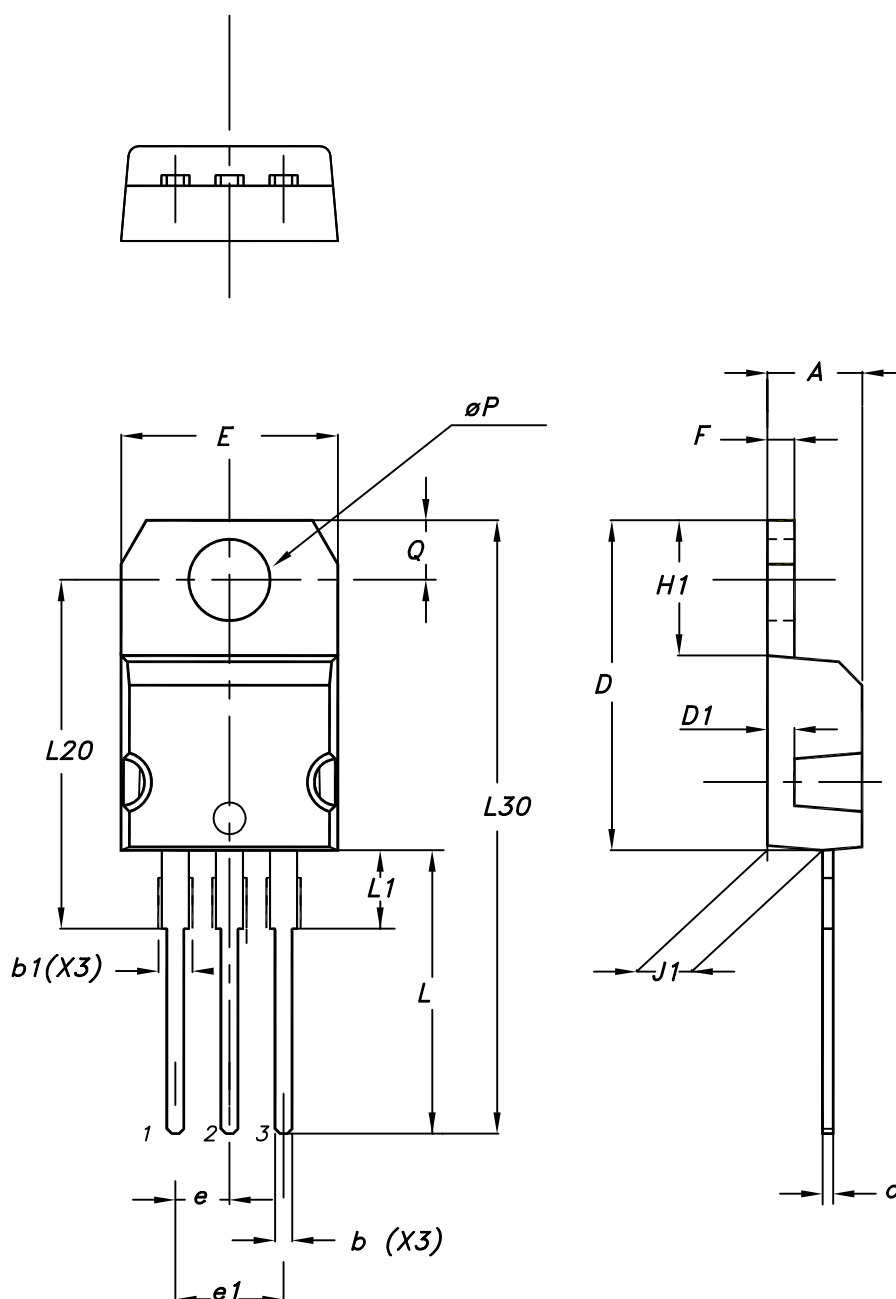

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Table 11. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

4.5 TO-220 type A package information

Figure 29. TO-220 type A package outline



0015988_typeA_Rev_21

Table 12. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

5 Ordering information

Table 13. Order codes

Order code	Marking	Package	Packing
STD18N55M5	18N55M5	DPAK	Tape and reel
STP18N55M5		TO-220	Tube

Revision history

Table 14. Document revision history

Date	Version	Changes
09-Feb-2010	1	First release.
04-Mar-2011	2	– Document status promoted from preliminary data to datasheet; – Added new package, mechanical data: D²PAK.
22-Nov-2013	3	– Updated: title on the cover page and RDS(on) values. – Modified: EAS value and note 3 in Table 2 – Modified: RDS(on) value in Table 4, typical values in Table 5 and 7 – Updated: the entire Table 5 – Added: Section 2.1: Electrical characteristics (curves) – Updated: Section 4: Package mechanical data and Section 5: Packaging mechanical data – Updated: Figure 11 and 18 – Minor text changes.
03-Aug-2018	4	The part numbers STB18N55M5 and STF18N55M5 have been moved to a separate datasheet. Removed maturity status indication from cover page. The document status is production data. Updated title in cover page, Section 1 Electrical ratings, Section 2 Electrical characteristics and Section 4 Package information. Minor text changes.

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